

Title (en)

DEVICE FOR FIXING A HEAT DISTRIBUTION COVER ON A PRINTED CIRCUIT BOARD

Title (de)

VORRICHTUNG ZUM BEFESTIGEN EINER WÄRMEVERTEILUNGSABDECKUNG AUF EINER LEITERPLATTE

Title (fr)

DISPOSITIF DESTINE A FIXER UN COUVERCLE DE REPARTITION DE CHALEUR SUR UNE CARTE DE CIRCUIT IMPRIME

Publication

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Application

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Priority

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- DE 10017925 A 20000411

Abstract (en)

[origin: WO0178142A1] The invention relates to a device for fixing a heat distribution cover (1) on a printed circuit board (2), comprising a plurality of electronic components (4) and a printed conductor level (5) as well as at least one fixing foot (7), which supports a fixing element (8) that can engage with the heat distribution cover (1).

IPC 1-7

H01L 23/40; **H05K 3/34**

IPC 8 full level

H05K 7/20 (2006.01)

CPC (source: EP KR US)

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